PCN # 2161

DATE: June 18, 2021

EXPECTED PCN SHIP DATE: June 18, 2021

☐ **PROCESS CHANGE NOTICE**
☒ **PRODUCT CHANGE NOTICE**

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

☐ DESIGN	☐ WAFER FAB	☒ ASSEMBLY	☐ TEST	☐ ELEC/MECH SPECS

AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: - For automotive products in TQFN/TDFN packages, body size 2x2mm to 7x7mm, Au wire size 0.8/1.0/1.3/2.0 mil Current mold compound Sumitomo G770HJ used at Assembler Vendor ASECL (ASE/CHUNG-LI/Taiwan).	CHANGE TO: - The replacement mold compound Sumitomo G700LA will be used for these devices at the same Assembly Vendor ASECL. This mold compound is an existing standard encapsulant for many other Maxim devices at this site.

JUSTIFICATION: Industry shortage of Sumitomo G770HJ requires that Maxim convert these devices to Sumitomo G700LA mold compound to ensure continuity of supply.

Maxim uses G700LA mold compound for many other automotive devices that are shipping in high volume since 2017.

- The AECQ-100 Qualification report is attached.
- Technical specification sheet G770HJ vs. G700LA is attached.
- Samples will be built upon request.
- There are no regulatory compliance changes to the material content of the devices.
- There are no changes to the form/fit/function of these devices using the new mold compound.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative   or   Nasser AliChaouche, PCN Coordinator
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